

BB02-EC :- 1.27mm x 2.54mm (0.05" x 0.1") DUAL ROW SOCKET, STRAIGHT, THROUGH HOLE - 6 TO 70 CONTACT

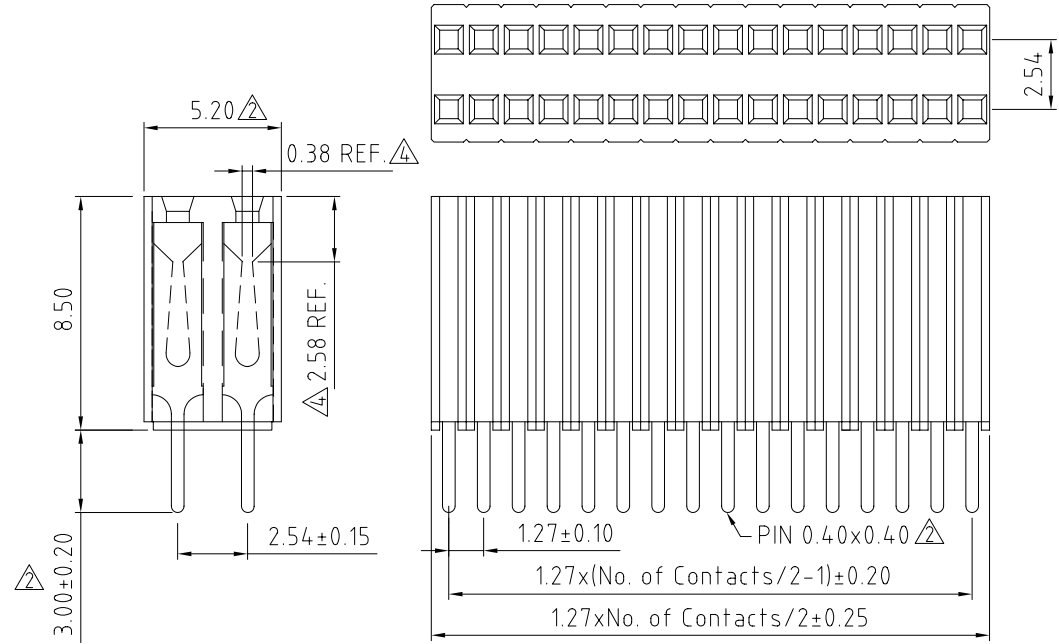
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	POLYESTER UL 94V-0 STANDARD NYLON 6T
PLATING	GOLD, TIN OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC WAVE: 230°C FOR 5-10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

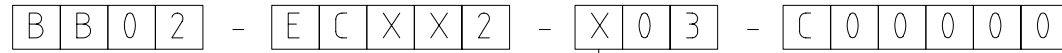
NOTES:

1. PACKED IN TUBE OR TRAY.
2. RECOMMENDED MATING PIN LENGTH: 4.5MM.  $\Delta$

MATES WITH :- BB02-DA  
BB02-DE  
BB02-DF  
BB02-DG

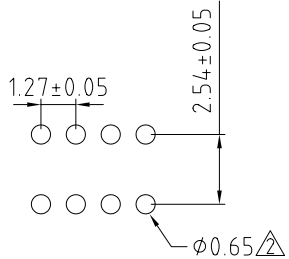


HOW TO ORDER



NO. OF CONTACTS  
 $\Delta$  06 TO 70

- CONTACT PLATING OPTIONS
- K = GOLD FLASH (STANDARD)
  - A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
  - B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
  - C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
  - T = BRIGHT TIN
  - M = MATT TIN
  - D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL
  - E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
  - F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
  - G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL



RECOMMENDED PC BOARD HOLE LAYOUT  
(TOLERANCE: ±0.05)

REV.	DATE	BY	DESCRIPTION
10	23/06/02	-	AXI RELEASE
11	22/02/05	NYW	DRW MODIFICATION
12	25/07/05	NYW	AMEND NO. OF CONTACTS
13	24/07/06	NYW	AMEND INSULATOR DIM. AMEND PCB LAYOUT. AMEND PIN DIMENSION.
14	05/06/07	NYW	DRAWING MODIFICATION. ADD CONTACT DIM. ADD NOTES 2.
15	21/05/08	CHC	PLATING MODIFICATION.
16	30/12/08	CHC	DRAWING MODIFICATION.

Scale:	5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material	SEE NOTE
Drawn:	CHC				
App'd:	XXXX	Title	SOCKET		NOT TO SCALE
Date:	30 DEC '08	Revision:	16	UNIT:	mm

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Type:	BB02-EC
Drawing Number:	BB02-EC
Sheet	1 of 1
Drawing	© E and O E